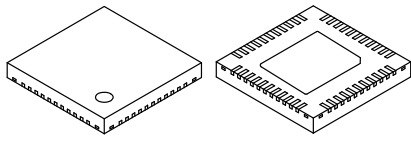


MECHANICAL CASE OUTLINE

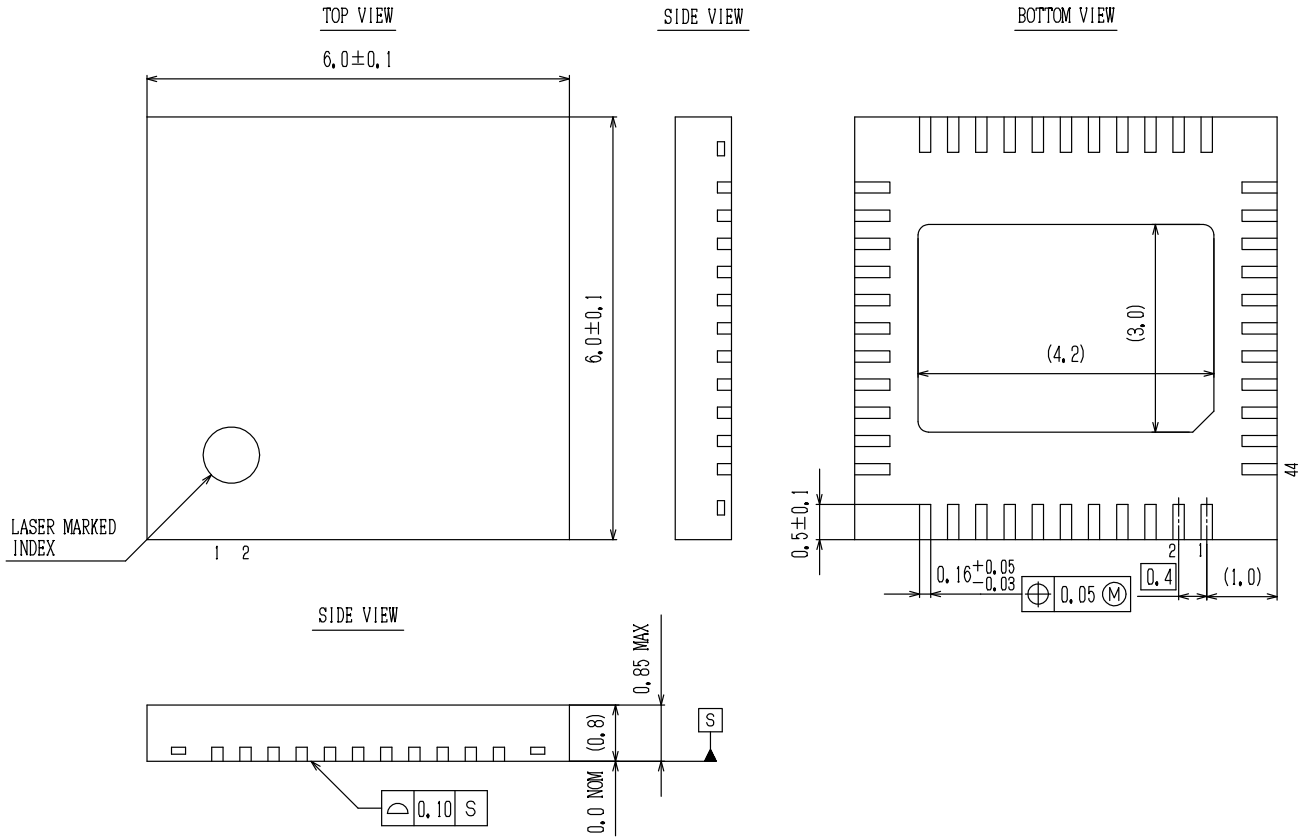
PACKAGE DIMENSIONS

ON Semiconductor®

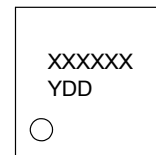
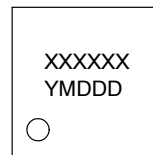


QFN44 6x6, 0.4P / VQFN44L
CASE 485CL
ISSUE A

DATE 05 DEC 2013



GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code
 Y = Year
 M = Month
 DDD = Additional Traceability Data

XXXXXX = Specific Device Code
 Y = Year
 DD = Additional Traceability Data

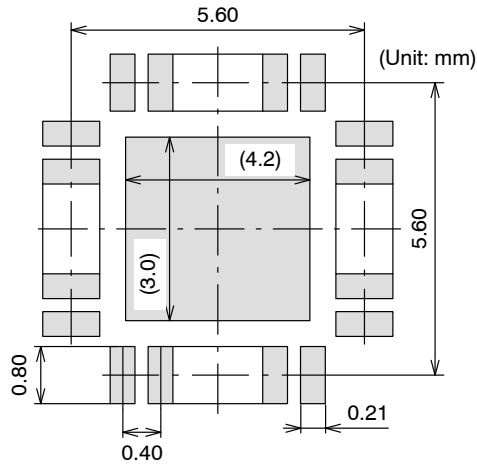
*This information is generic. Please refer to device data sheet for actual part marking.
 Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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SOLDERING FOOTPRINT*



NOTES:

1. The measurements are not to guarantee but for reference only.
2. Module level verification after set designing must be implemented. Validating solderability and Reliability verification for joint areas such as Exposed Die-pad and must be carried out.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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